

Dual N-Channel Enhancement Mode Power MOSFET **MX8205S**

## DESCRIPTION

The MX8205S uses advanced trench technology to provide excellent  $R_{DS(ON)}$  and low gate charge. It can be used in a wide variety of applications.

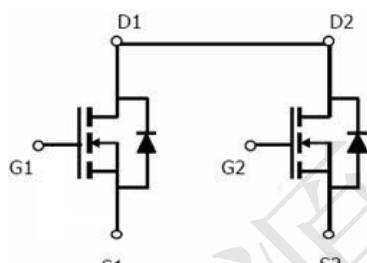
## GENERAL FEATURES

- $V_{DS}=20V$ ,  $I_D=5A$
- $R_{DS(ON)}(\text{Typ.})=19m\Omega$  @  $V_{GS}=4.5V$
- $R_{DS(ON)}(\text{Typ.})=20m\Omega$  @  $V_{GS}=3.9V$
- $R_{DS(ON)}(\text{Typ.})=30m\Omega$  @  $V_{GS}=2.5V$
- Surface Mount Package
- Advanced trench cell design

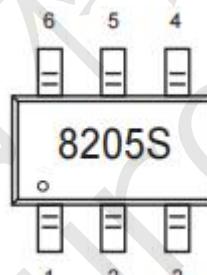
## APPLICATION

- Battery protection
- Load switch

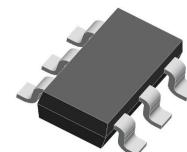
## PINOUT



Schematic diagram



Marking and Pin Assignment



SOT23-6L top view

## ORDERING INFORMATION

Part Number	Storage Temperature	Package	Devices Per Reel
MX8205S	-55°C to 150°C	SOT23-6L	-

## ABSOLUTE MAXIMUM RATINGS ( $T_A=25^\circ C$ unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	$V_{DS}$	20	V
Gate-Source Voltage	$V_{GS}$	$\pm 12$	V
Drain Current-Continuous <sup>(Note1)</sup>	$I_D$	5	A
Pulsed Drain Current <sup>(Note2)</sup>	$I_{DM}$	20	A
Total Power Dissipation <sup>(Note1)</sup>	$P_{tot}$	0.83	W
Operating Junction and Storage Temperature Range	$T_J, T_{STG}$	-55 to 150	°C
Diode Forward Current <sup>(Note1)</sup>	$I_S$	5	A

## THERMAL RESISTANCE

Thermal Resistance, Junction-to-Ambient <sup>(Note1)</sup>	$R_{\theta JA}$	150	°C/W
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Note 1. Surface Mounted on 1 in<sup>2</sup> pad area, t ≤ 10 sec.

Note 2. Pulse Width ≤ 300μs, duty cycle ≤ 2%.

**ELECTRICAL CHARACTERISTICS**( $T_A=25^\circ\text{C}$  unless otherwise noted)

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
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**Off Characteristics**

Drain-Source Breakdown Voltage	$\text{BV}_{\text{DSS}}$	$V_{\text{GS}}=0\text{V}, I_{\text{D}}=250\mu\text{A}$	20	-	-	V
Zero Gate Voltage Drain Current	$I_{\text{DSS}}$	$V_{\text{DS}}=20\text{V}, V_{\text{GS}}=0\text{V}$	-	-	1	$\mu\text{A}$
Gate-Body Leakage Current	$I_{\text{GSS}}$	$V_{\text{GS}}=\pm 10\text{V}, V_{\text{DS}}=0\text{V}$	-	-	$\pm 100$	nA

**On Characteristics**

Gate Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{DS}}=V_{\text{GS}}, I_{\text{D}}=250\mu\text{A}$	0.5	0.87	1.2	V
Drain-Source On-State Resistance <sup>(Note3)</sup>	$R_{\text{DS}(\text{ON})}$	$V_{\text{GS}}=4.5\text{V}, I_{\text{D}}=5\text{A}$	-	19	24	$\text{m}\Omega$
		$V_{\text{GS}}=3.9\text{V}, I_{\text{D}}=4.5\text{A}$	-	20	25	$\text{m}\Omega$
		$V_{\text{GS}}=2.5\text{V}, I_{\text{D}}=3.5\text{A}$	-	30	35	$\text{m}\Omega$

**Dynamic Characteristics**<sup>(Note4)</sup>

Input Capacitance	$C_{\text{iss}}$	$V_{\text{DS}}=8\text{V}, V_{\text{GS}}=0\text{V}, F=1.0\text{MHz}$	-	802	-	pF
Output Capacitance	$C_{\text{oss}}$		-	153	-	pF
Reverse Transfer Capacitance	$C_{\text{rss}}$		-	122	-	pF

**Switching Characteristics**<sup>(Note4)</sup>

Turn-on Delay Time	$t_{\text{d}(\text{on})}$	$V_{\text{DS}}=10\text{V}, I_{\text{DS}}=1\text{A}$ $V_{\text{GS}}=4.5\text{V}, R_{\text{G}}=1.6\Omega$ $R_{\text{GEN}}=10\Omega$	-	18	-	nS
Turn-on Rise Time	$t_{\text{r}}$		-	5	-	nS
Turn-Off Delay Time	$t_{\text{d}(\text{off})}$		-	43.8	-	nS
Turn-Off Fall Time	$t_{\text{f}}$		-	20	-	nS
Total Gate Charge	$Q_{\text{g}}$	$V_{\text{DS}}=10\text{V}, I_{\text{DS}}=4\text{A}$ $V_{\text{GS}}=4.5\text{V}$	-	10.5	-	nC
Gate-Source Charge	$Q_{\text{gs}}$		-	2	-	nC
Gate-Drain Charge	$Q_{\text{gd}}$		-	2.5	-	nC

**Drain-Source Diode Characteristics**

Diode Forward Voltage <sup>(Note 3)</sup>	$V_{\text{SD}}$	$V_{\text{GS}}=0\text{V}, I_{\text{SD}}=1\text{A}$	-	-	1.2	V
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Note 3. Pulse Test: Pulse Width  $\leq 300\mu\text{s}$ , Duty Cycle  $\leq 2\%$ .

Note 4. Guaranteed by design, not subject to product.



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ShenZhen ChipSourceTek Technology Co., Ltd.

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## TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

Figure 1. Power Capability

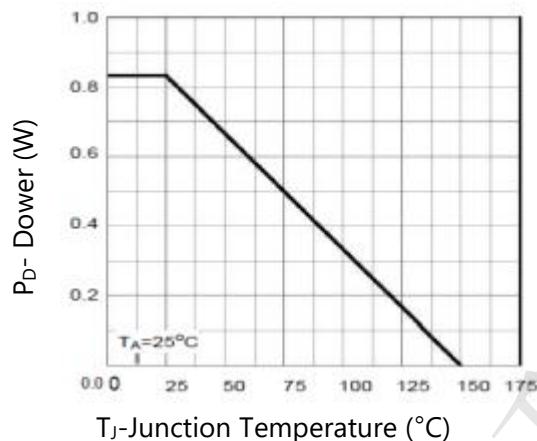


Figure 2. Current Capability

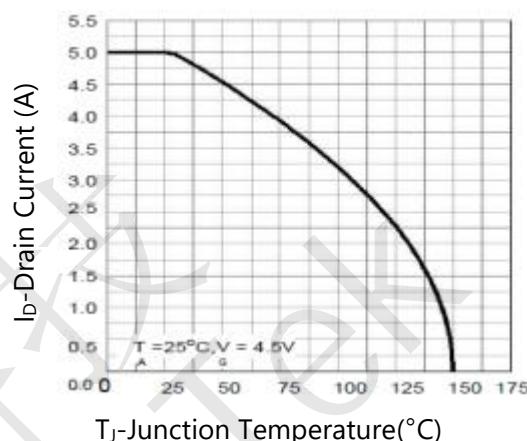


Figure 3. Safe Operation Area

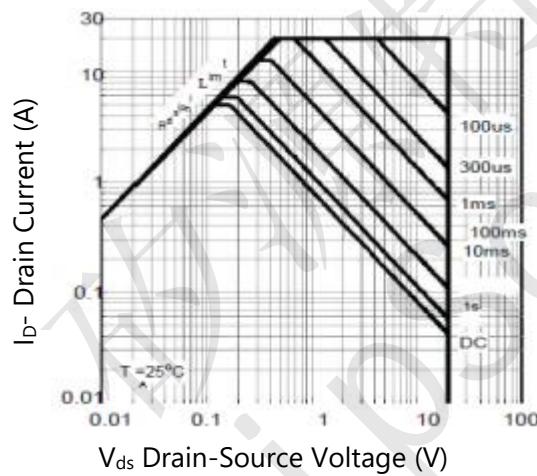


Figure 4. Transient Thermal Impedance

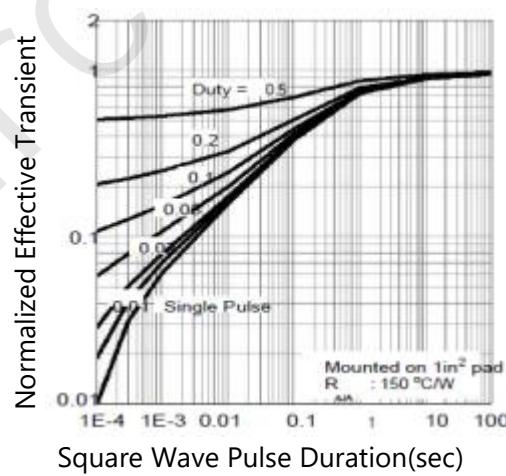


Figure 5. Output Characteristics

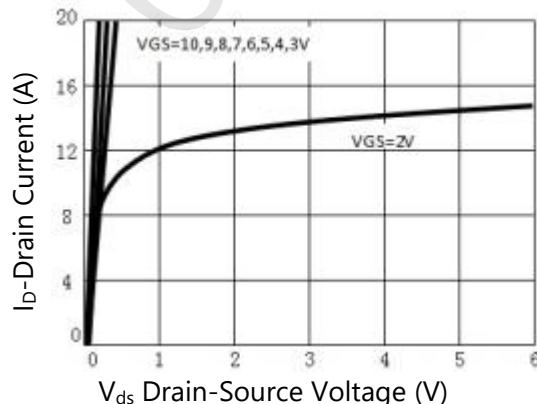
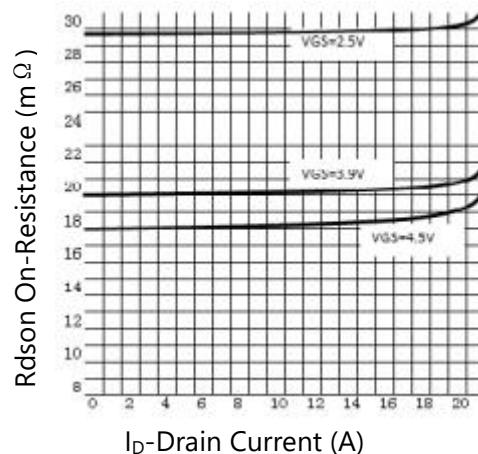


Figure 6.  $R_{dson}$  vs Drain Current





## TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

Figure 7. Transfer Characteristics

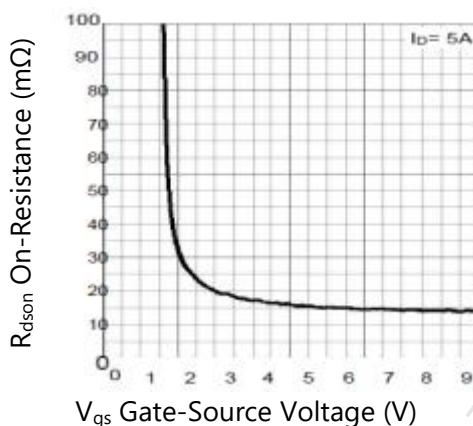


Figure 8. Normalized Threshold Voltage

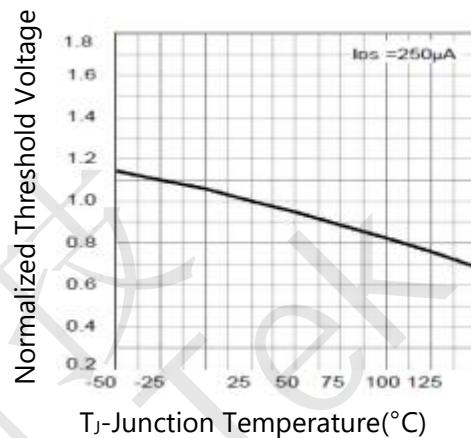


Figure 9. Normalized On Resistance

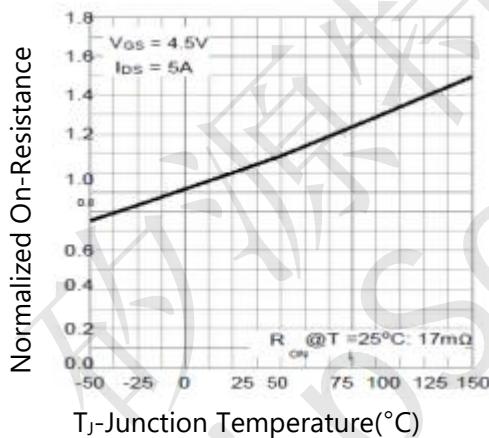


Figure 10. Diode Forward Current

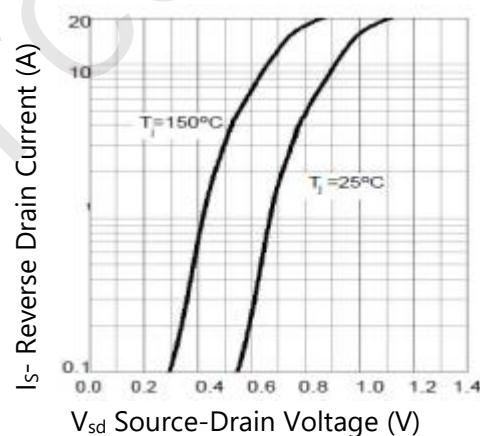


Figure 11. Capacitance

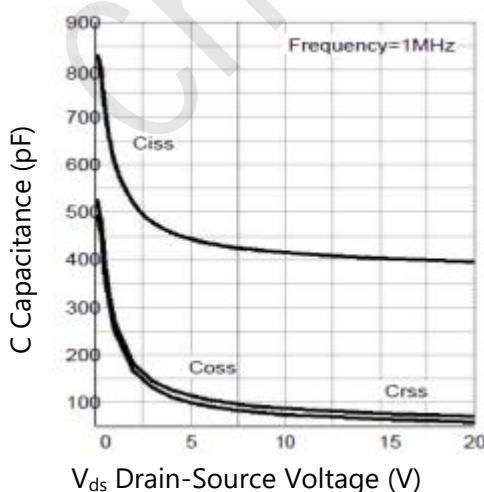
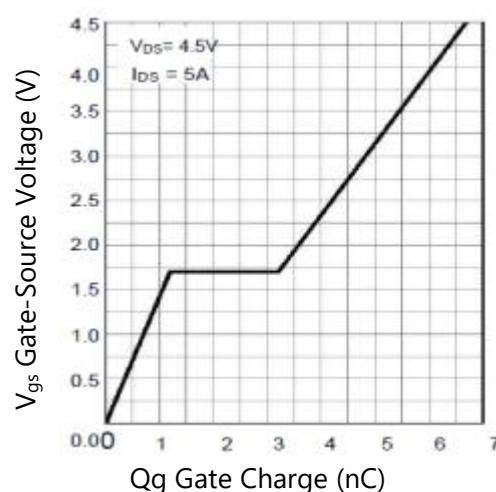


Figure 12. Gate Charge





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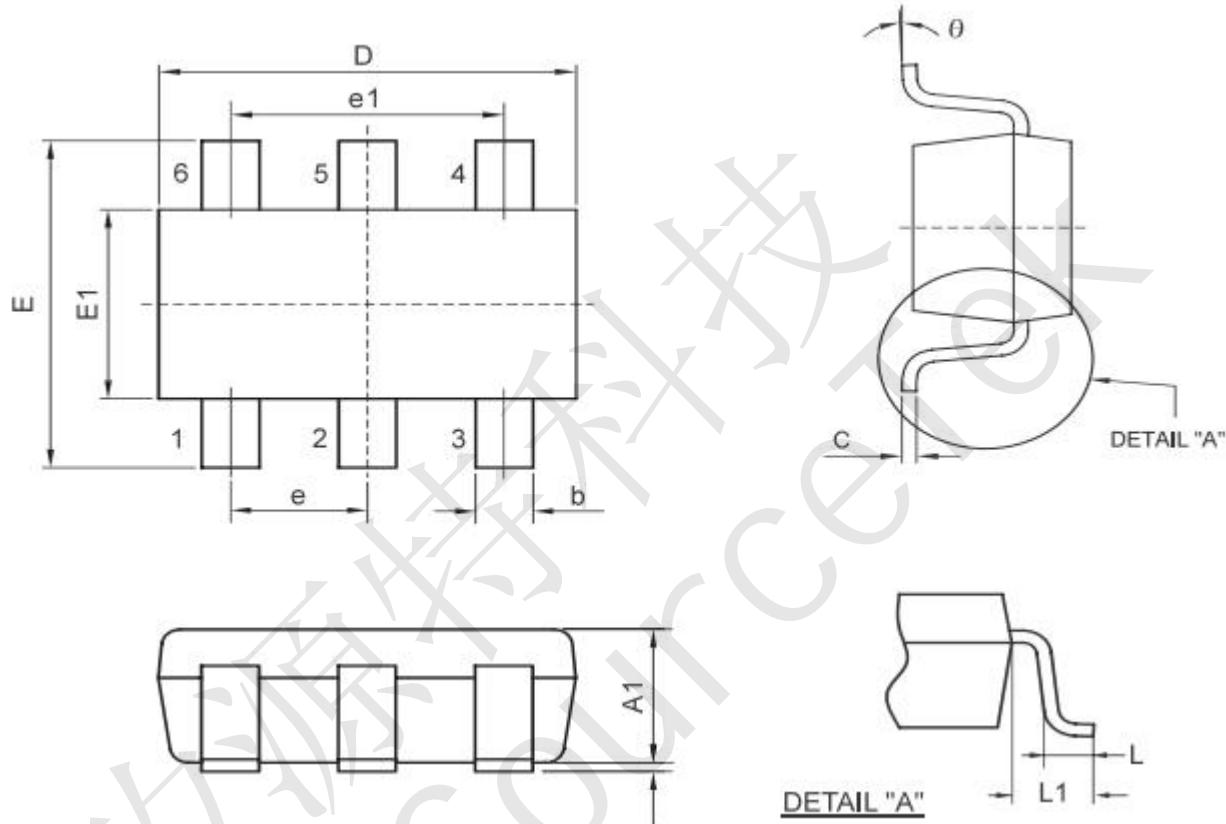
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## PACKAGE INFORMATION

### SOT23-6L



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
D	2.692	3.099	0.106	0.122
E	2.591	3.000	0.102	0.118
E1	1.397	1.803	0.055	0.071
e	0.950 REF.		0.037 REF.	
e1	1.900 REF.		0.075 REF.	
b	0.300	0.500	0.012	0.020
C	0.080	0.200	0.003	0.008
A	0.000	0.100	0.000	0.004
A1	0.700	1.200	0.028	0.048
L	0.300	0.600	0.012	0.024
L1	0.600 REF.		0.023 REF.	
θ	0°	9°	0°	9°